

2826 #



PATENT APPLICATION  
Do. No. 9903-045

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Sang-Ho AHN and Se-Yong OH

Serial No. 10/008,704

Examiner: Tran, Tan N

Confirmation No. 8392

Filed: December 6, 2001

Group Art Unit: 2826

For: ULTRA-THIN SEMICONDUCTOR PACKAGE DEVICE AND METHOD  
FOR MANUFACTURING THE SAME

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JAN 29 2003  
TECHNOLOGY CENTER 2800

Assistant Commissioner for Patents,  
Washington, D.C. 20231

Responsive to the Office Action dated September 23, 2002, enclosed is an amendment in the above-identified application.

The fee has been calculated as shown below.

CLAIMS AS AMENDED					
For:	Number After Amendment	Previous Number	Extra	Rate	Additional Fee
Total Claims	92	53	39	x \$18 =	\$702.00
Independent Claims	8	5	3	x \$84 =	\$252.00
Extension of Time - 1 <sup>st</sup>					\$110.00
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT					\$1064.00

\*greater of twenty (20) or number for which fee has been paid

\*\*greater of three (3) or number for which fee has been paid

- ☒ PTO Form 2038 authorizing credit card payment for the above-listed fees is enclosed.  
☒ Any deficiency or overpayment should be charged or credited to deposit account number 13-1703.

Respectfully submitted,

MARGER JOHNSON & McCOLLOM, P.C.



20575

PATENT TRADEMARK OFFICE

01/24/2003 HBIZUNES 00000028 10008704.

04 FC:1251

110.00 OP

Alan T. McCollom  
Reg. No. 28,881

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I HEREBY CERTIFY THAT THIS CORRESPONDENCE IS BEING DEPOSITED WITH THE UNITED STATES POSTAL SERVICE AS FIRST CLASS MAIL BY AN ENVELOPE ADDRESSED TO:  
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1-17-03



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BOX NON FEE AMENDMENT  
Assistant Commissioner for Patents  
Washington, D.C. 20231

01/24/2003 MBIZUNES 00000028 10008704

01 FC:1806  
02 FC:1202  
03 FC:1201

180.00 BP  
702.00 OP  
252.00 OP

RECEIVED  
JAN 29 2003  
TECHNOLOGY CENTER 2826

2/3/03  
Schmith

RESPONSE TO OFFICE ACTION

02/04/2003 ASMITH 00000002 131703 10008704  
Responsive to the Office Action, dated September 23, 2002, please amend the  
application as follows.  
01 FC:1201 84.00 CH  
02 FC:1202 360.00 CH

IN THE CLAIMS

A full set of pending claims, including any amendments or cancellations as of this response, is as follows:

1. An ultra-thin semiconductor package device comprising:  
a lead frame comprising a die pad, a plurality of leads disposed around the die pad, and tie bars connected to and disposed around the die pad, wherein said die pad comprises a chip attaching part and a peripheral part surrounding the chip attaching part;  
a semiconductor chip mounted to the die pad chip attaching part, said chip having a plurality of electrode pads, wherein the plurality of electrode pads are electrically interconnected to the leads; and wherein each of the leads comprises integrally connected inner leads and outer leads;  
an encapsulant encapsulating the semiconductor chip to form a package body, wherein said inner leads are encapsulated by the encapsulant and said outer leads are external to the encapsulant; and  
said chip attaching part having a first thickness and the inner leads having a second thickness greater than the first thickness.